

Faculty of Engineering
School of Photovoltaic and Renewable Energy Engineering



Beyond the Standard: What Your Module Qualification Isn't Telling You

PV ModuleTech USA, Napa Valley, USA, 16-17 June 2026

Bram Hoex

School of Photovoltaic and Renewable Energy Engineering, UNSW Sydney, Kensington, 2052, Australia

ARENA



Australian Government
Australian Renewable
Energy Agency



World-Leading PV Research Translated into Real Solutions

50+

Years of PV
research excellence

**PERC
& TOPCon**
Invented at UNSW

**World
Records**
Solar cell
efficiencies

200+
Researchers &
400+ students

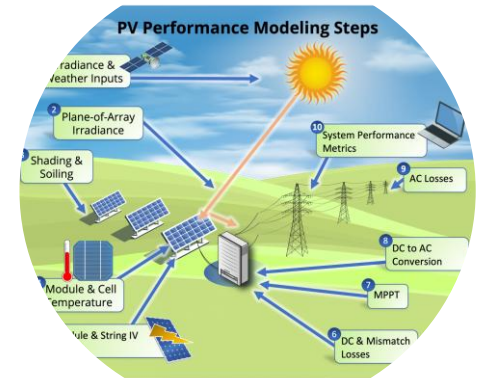
Strong commercialisation track record

Spin-offs, licensed IP, and industry partnerships delivering real-world impact

Foresight PV

Energy Yield & Degradation Modelling

Highest-precision energy yield modelling for utility-scale solar — advanced degradation analytics to maximise plant lifetime & returns.



Developers

Asset Owners

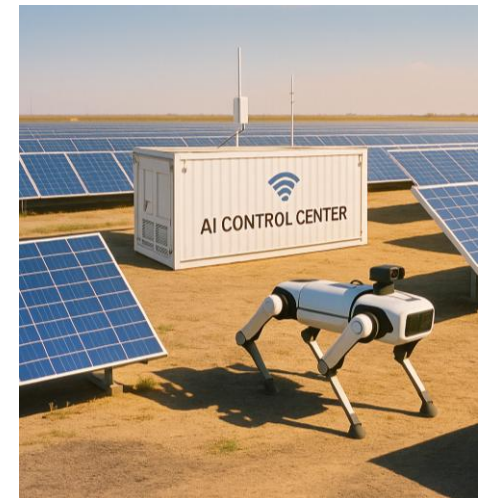
Module Mfrs



AI Solar Operations Platform

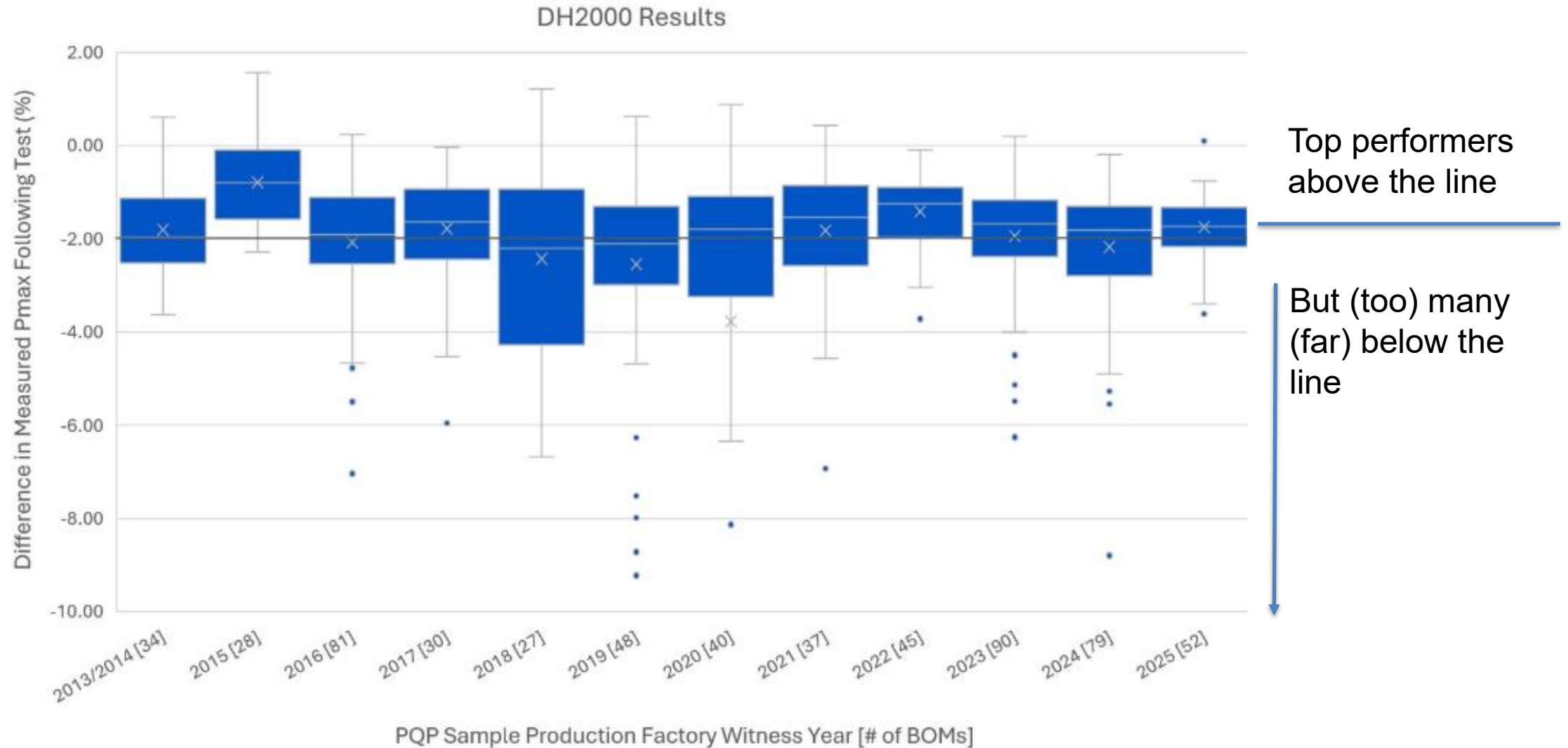
AI brain and robotic hands that make solar farms self-operating, efficient, and effortless.

LIVE: 18 utility-scale solar farms across MENA now live

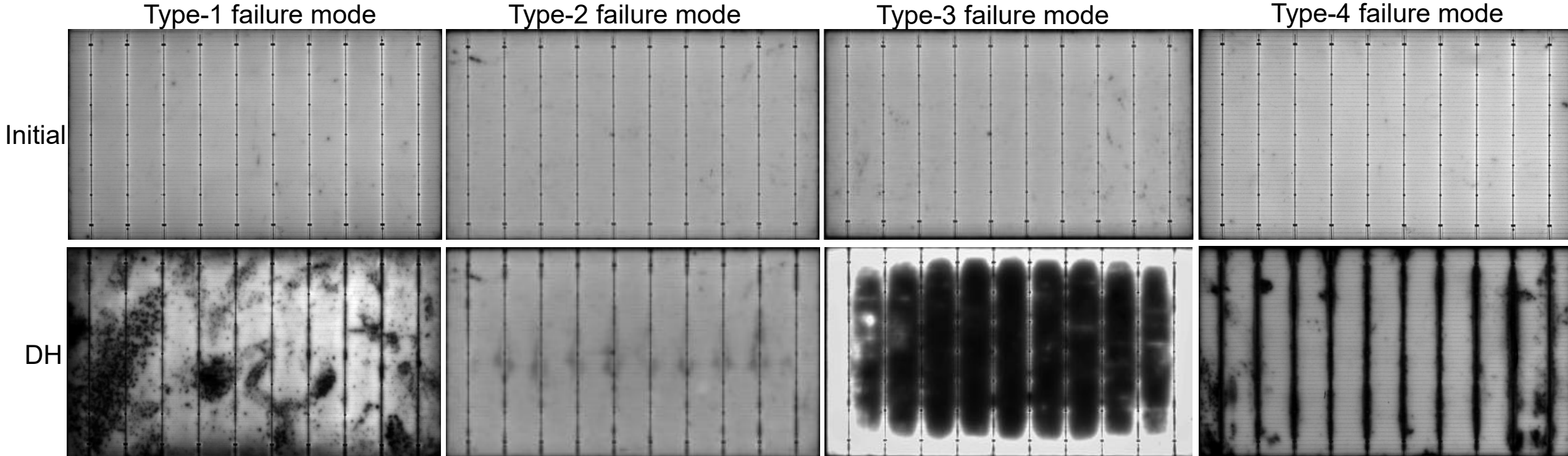


Stress Factors	Drivers of loss	Occurrence/Examples	Leads to
Humidity	Degradation of packaging materials	♦ Glass breakage ♦ Dielectric breakdown ♦ Bypass diode failure ♦ Encapsulant (discoloration, elasticity) ♦ Backsheet cracking/delamination	♦ Performance failure ♦ Safety hazard (electric shock) ♦ Ground faults/current leakage ♦ Electrochemical corrosion
UV			
High temp	Loss of adhesion	♦ Delamination: • Glass-to-encapsulant • Cell-to-encapsulant • Encapsulant-to-backsheet	♦ Optical decoupling (reduced light transmission) ♦ Inefficient heat dissipation ♦ Reverse-bias cell heating ♦ Higher operating temperatures
T-cycling	Degradation of cell/module interconnects	♦ Change in joint geometry ♦ Thermomechanical fatigue ♦ Solder bond failure ♦ Broken interconnect	♦ Increased series resistance ♦ Increased heating & Localized hot spots ♦ Burns (solder joints, backsheet, encapsulant) ♦ Arcing due to opencircuit
High voltage	Degradation caused by moisture intrusion	♦ Corrosion of metallization ♦ Delamination	♦ Failed gridline-to-cell adhesion ♦ Increased electrical conductivity of materials ♦ Increased current leakage ♦ PID
Mechanical	Degradation of semiconductor device	♦ Cracks in cells ♦ Diffusion of impurity to cell surface	♦ Electrical isolation
Eventually results in safety issues, performance reduction, or failure			

Latest results from PVEL scorecard – Damp Heat Degradation

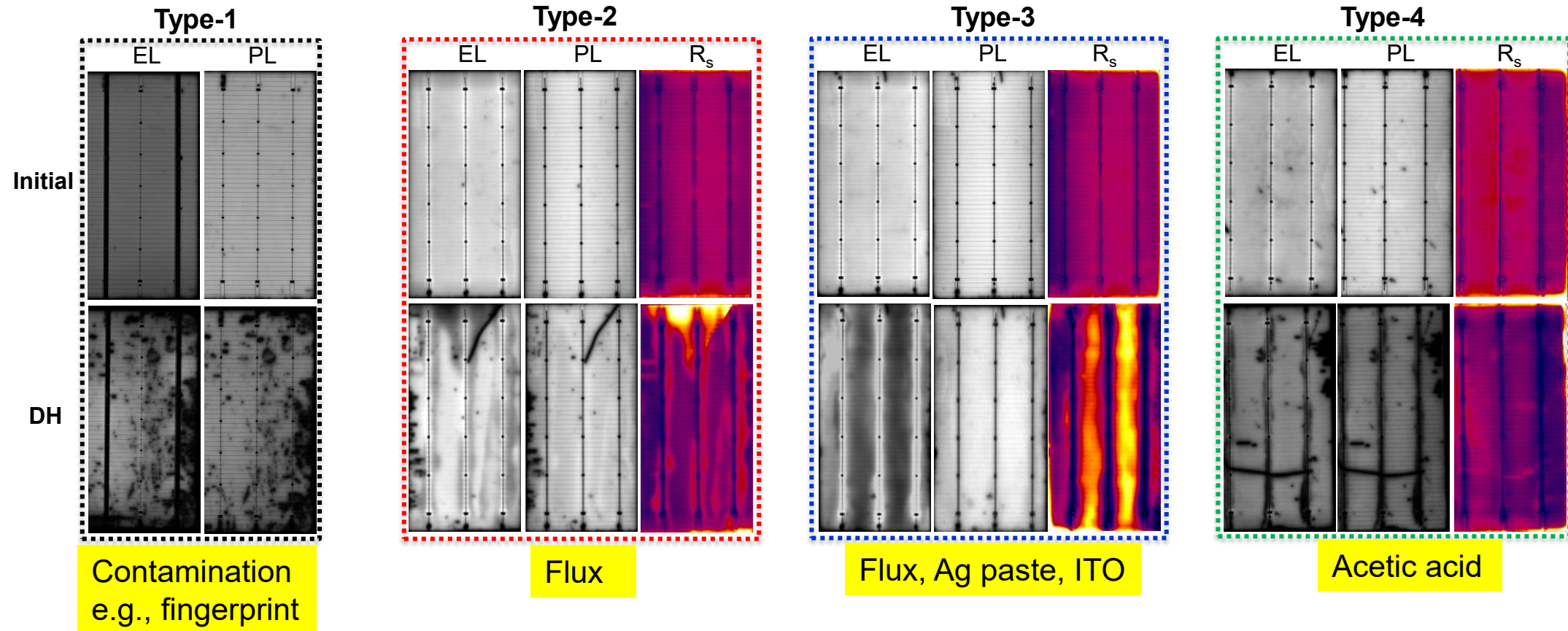


Four novel damp-heat failure modes in HJT solar cells



- Four main failure modes found on HJT glass-backsheet modules after the humidity test
 - Type-1 : **Point** failure ($P_{\max}$ loss of up to $\sim 40\%_{\text{rel}}$)
 - Type-2 : Failure **around** the interconnection of the busbar and ribbon ($P_{\max}$ loss $\sim 5\%_{\text{rel}}$)
 - Type-3 : Failure **between** interconnection of busbar and ribbon ($P_{\max}$ loss of up to $\sim 50\%_{\text{rel}}$)
 - Type-4 : Failure **at/on** the interconnection or busbar and ribbon ($P_{\max}$ loss of up to $\sim 16\%_{\text{rel}}$)
- Each failure mode required different approaches to detect and eliminate at the cell level

Four novel damp-heat failure modes in HJT solar cells

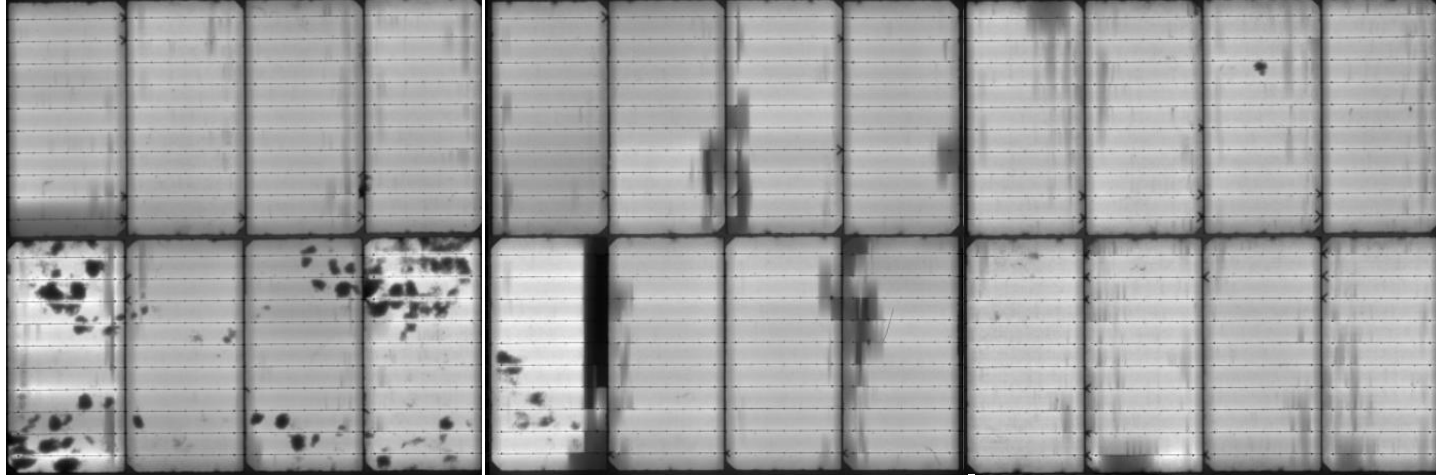


- All four failure modes can be reproduced in the non-encapsulated cells
- Root causes responsible for each failure mode have been identified
- Cell-level testing is one order of magnitude quicker than module-level testing

Three failure modes in TOPCon modules

Type-1 failure mode Type-2 failure mode Type-3 failure mode

Initial

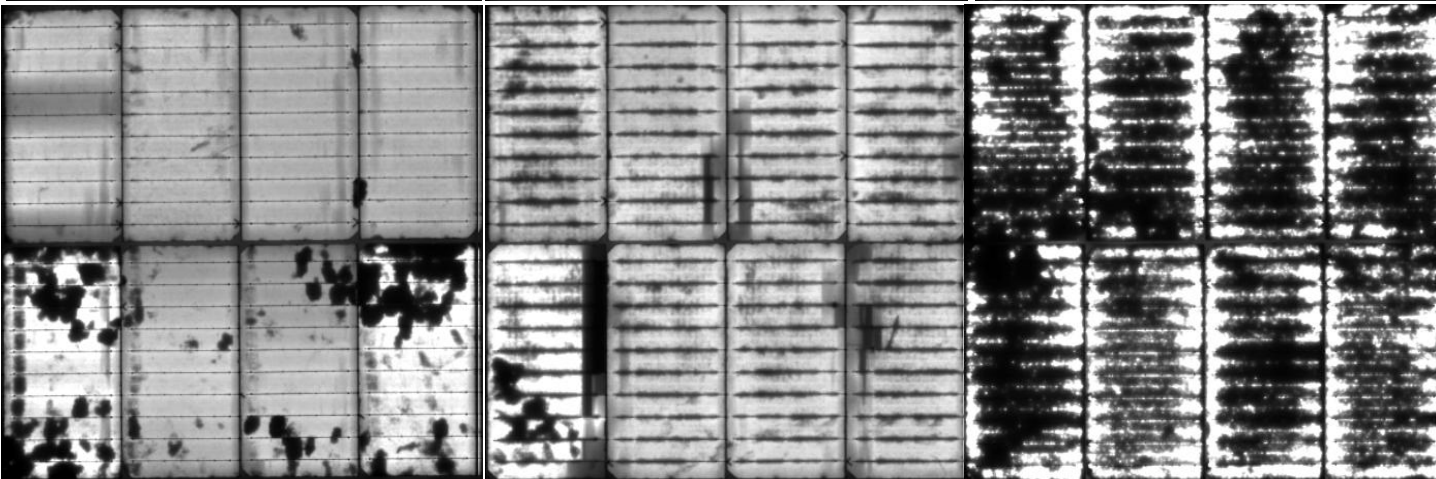


Type-1 failure mode: point-localized failure

Type-2 failure mode: failure at/around the interconnection point

Type-3 failure mode: failure across the entire area of cells/module

DH1000h



$P_{\max}$ loss ~15%_{rel}

$P_{\max}$ loss ~11%_{rel}

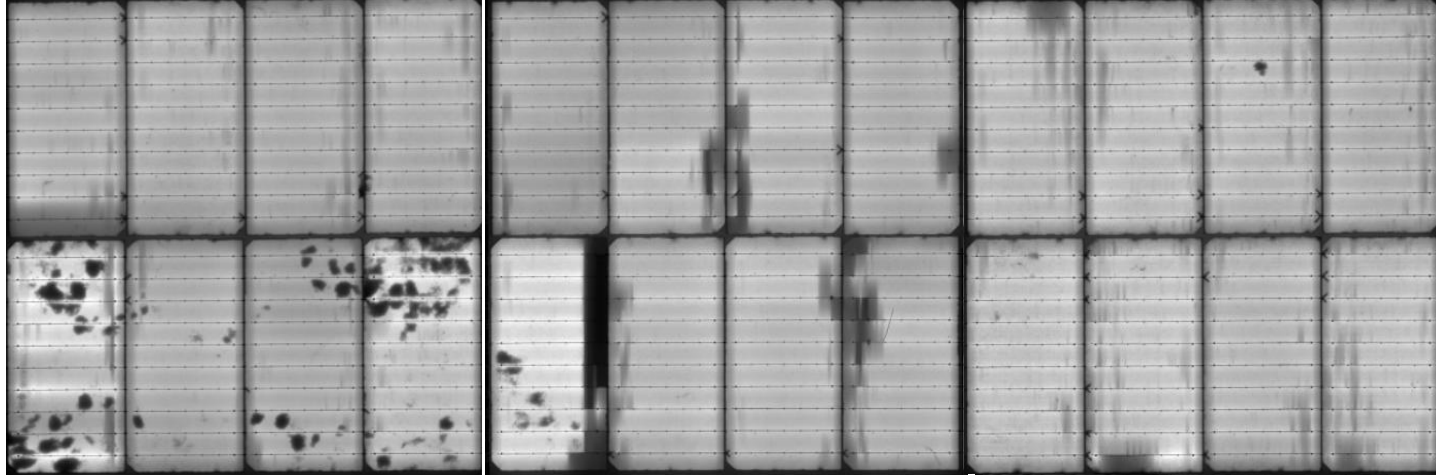
$P_{\max}$ loss ~65%_{rel}

- Three failure modes have been realised in TOPCon modules, but absent in PERC modules
- These failure modes are quite similar to HJT modules

Three failure modes in TOPCon modules

Type-1 failure mode Type-2 failure mode Type-3 failure mode

Initial

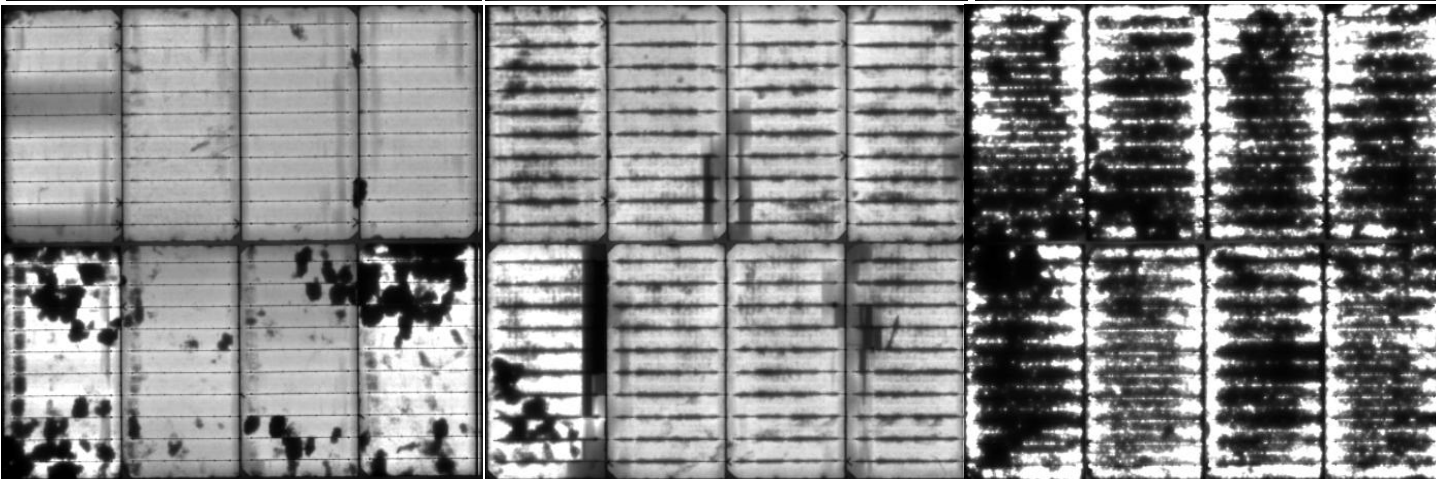


Type-1 failure mode: point-localized failure

Type-2 failure mode: failure at/around the interconnection point

Type-3 failure mode: failure across the entire area of cells/module

DH1000h



Contamination

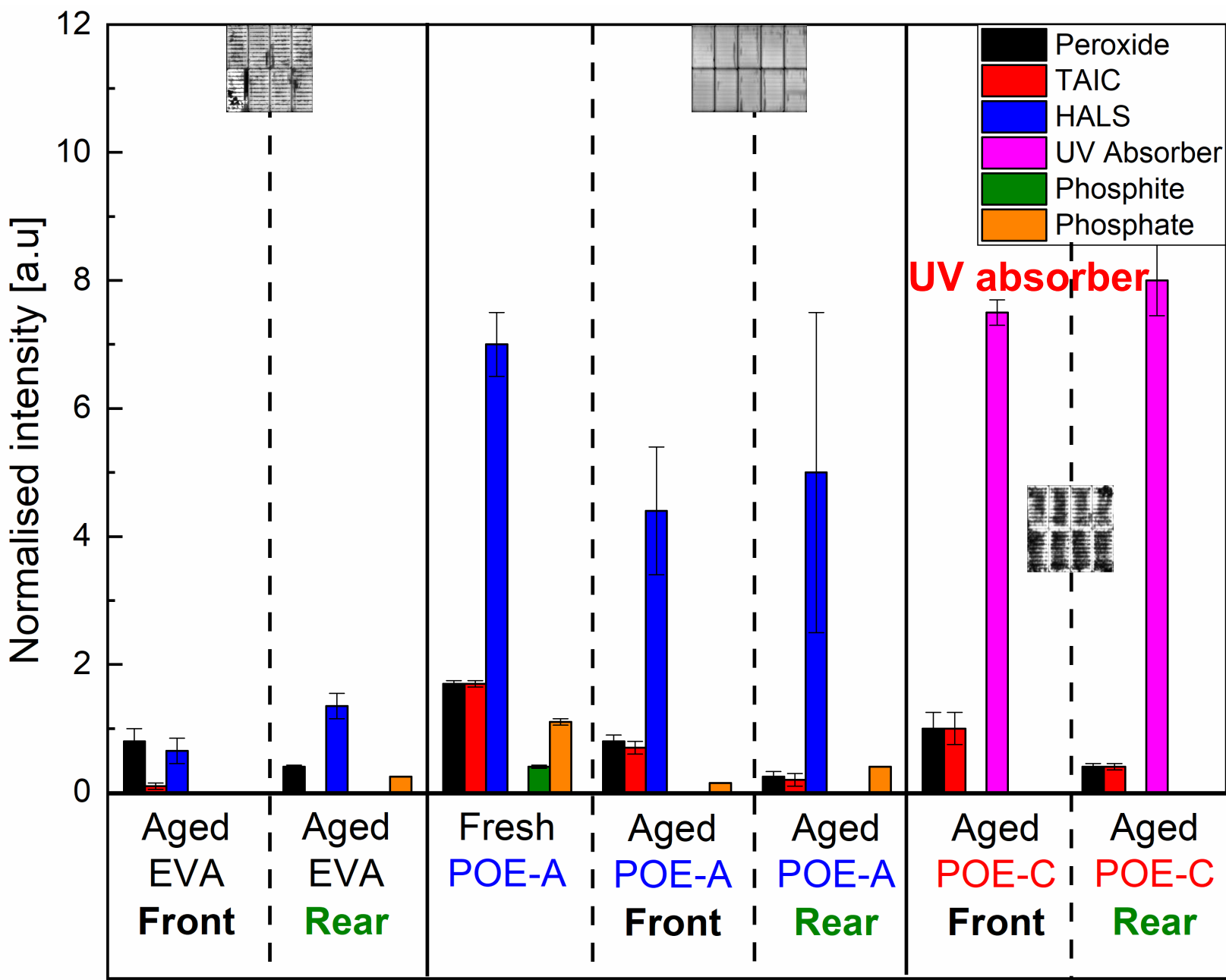
Acedic acid

Encapsulant additives

The Encapsulant Is a Chemical Reactor, Not Just Glue!

Additive class	Typical chemistries (examples)	Primary role(s)
Organic peroxides (crosslinkers)	Dicumyl peroxide (DCP); TBEC; DBPH (Luperox/Trigonox 101)	Generate radicals during lamination to crosslink polymer (raise gel content), improving creep and thermal resistance
Crosslinking coagents	TAIC (triallyl isocyanurate); TAC (triallyl cyanurate); TMPTMA	Boost crosslink efficiency/density and heat resistance at a given peroxide level; shorten lamination time
UV absorbers (UVAs)	Benzotriazoles (e.g., Tinuvin P/327/360); Benzophenones (UV-531); Hydroxyphenyl-triazines (HPTs)	Filter UV ($\approx 240\text{--}360$ nm) to slow photo-oxidation and yellowing
HALS (hindered amine light stabilizers)	Tinuvin 770/292/123; reactive/grafted HALS	Catalytically quench radicals; synergistic with UVAs for long-term weatherability
Antioxidants — primary & secondary	Primary phenolics (Irganox 1010/1076); Secondary phosphites (Irgafos 168)	Limit thermo-oxidative degradation during processing and service; phenolics trap radicals, phosphites decompose hydroperoxides
Adhesion promoters (silane coupling agents)	γ -MPS/A-174 (3-methacryloxypropyl-trimethoxysilane); VTMS; silane-grafted tie-layers	Form covalent Si–O–Si bridges to glass/metal oxides $\rightarrow$ durable adhesion
Acid scavengers / neutralizers	Calcium stearate, Magnesium stearate, Magnesium oxide; Hydrotalcites (e.g., Mg–Al carbonate)	Neutralize acidic species (notably acetic acid from EVA hydrolysis) to mitigate corrosion/PID risk
Fillers / nanoparticles (optional)	Al ₂ O ₃ , SiO ₂ , ZnO, graphene (research)	Tune barrier/mechanical/UV shielding; processing aids
Luminescent down-shifting (UV-DS) materials	Phosphors (YAG:Ce, Sr ₂ SiO ₄ :Eu ²⁺); Quantum dots (e.g., AgInS ₂ /ZnS, InP/ZnS); organic dyes (coumarins/perylene)	Convert UV/near-UV photons to visible $\rightarrow$ boost short-wavelength response and reduce UV stress (UVID)

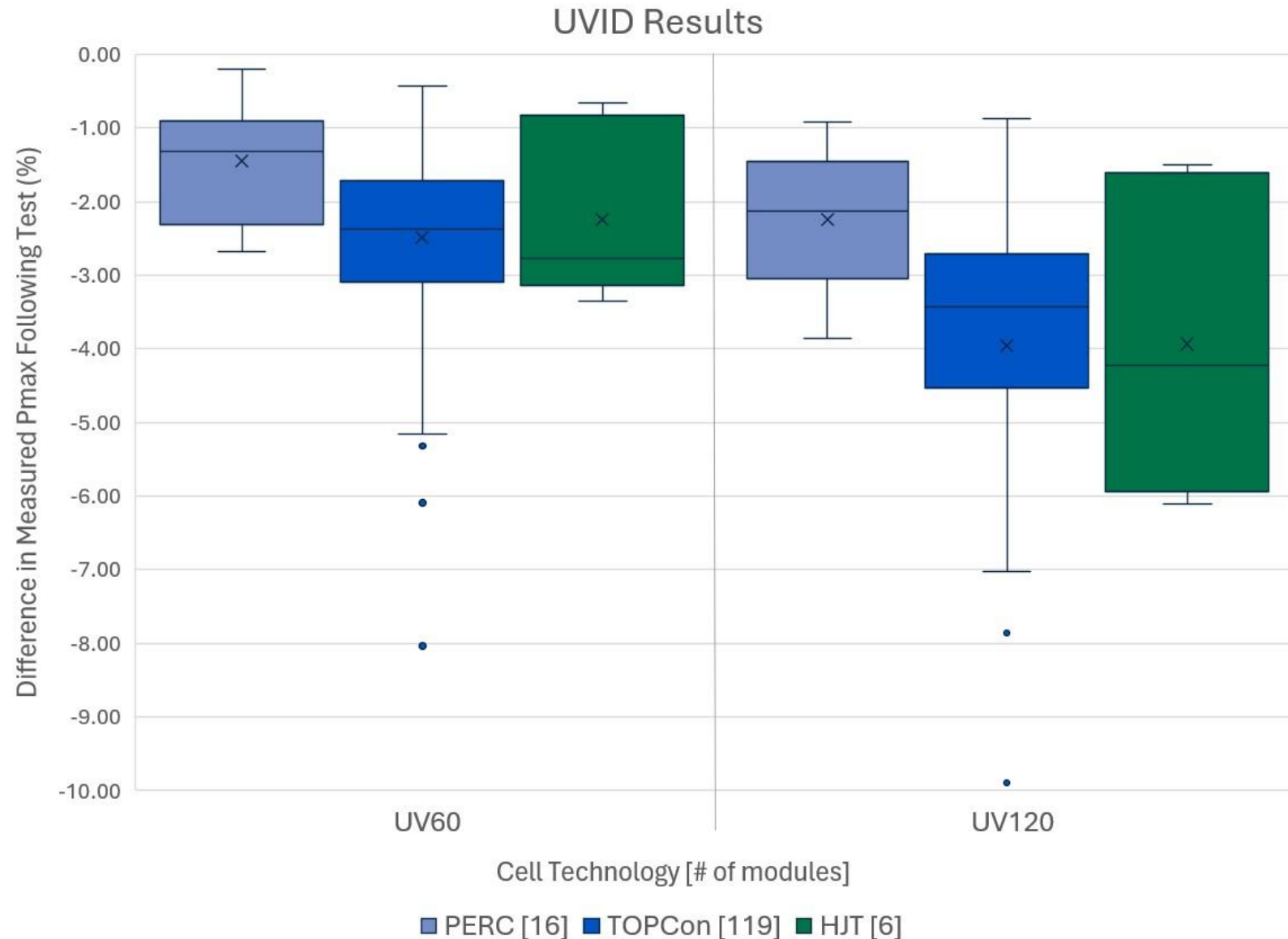
Root Cause for Catastrophic Failure Identified



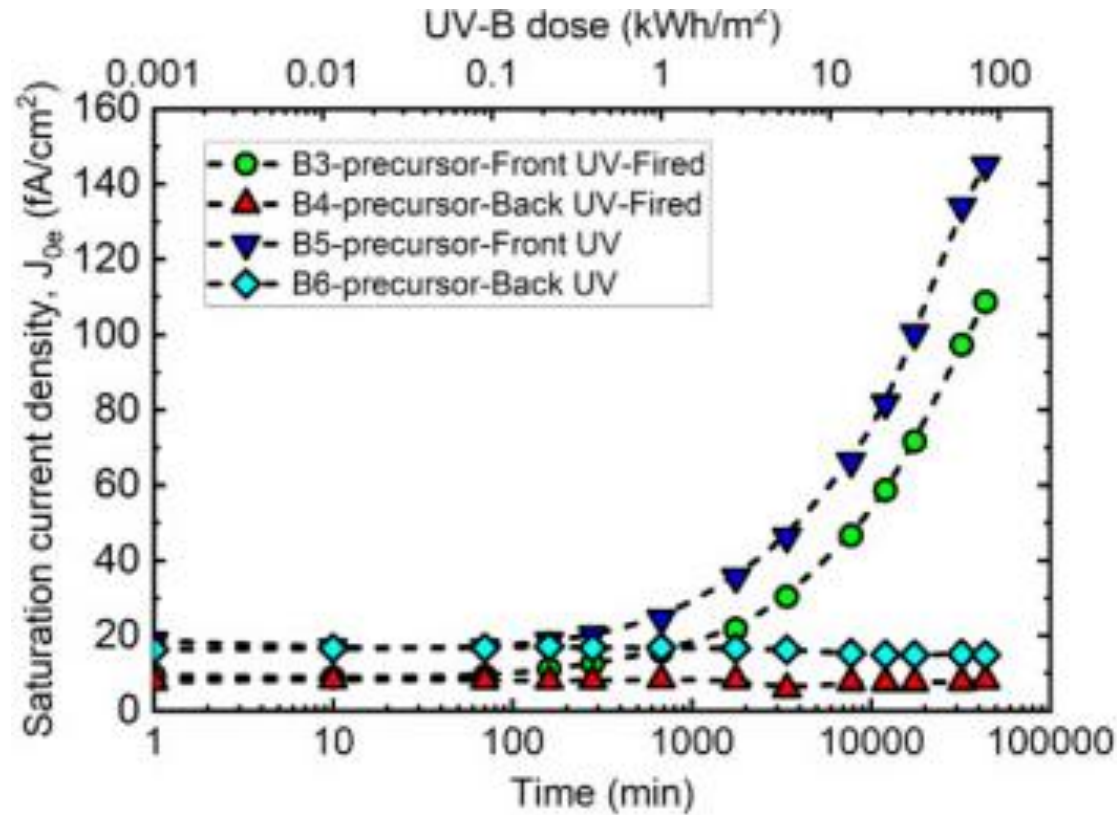
POE-C:

- Contains **UV absorber**
- No Phosphite/Phosphate (antioxidant)
→ Additive degrades, leads to acid formation - > degrades metallisation

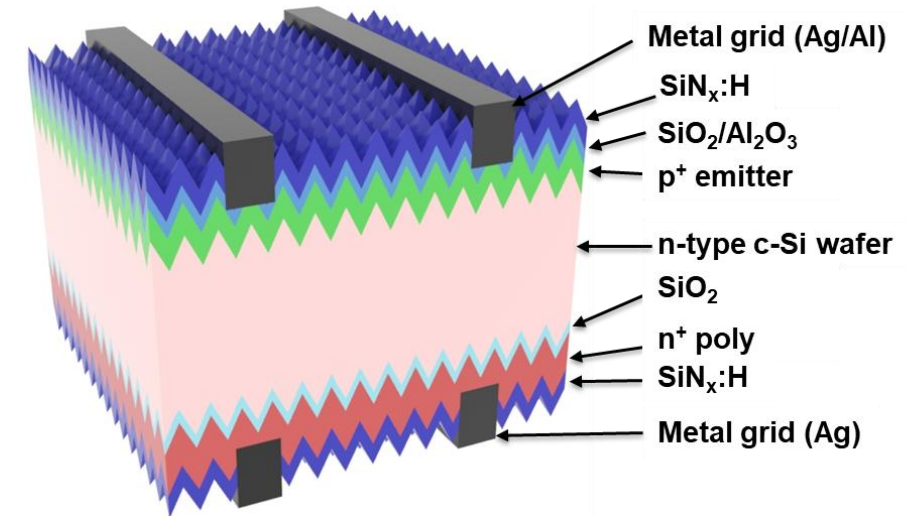
UVID Is a Fleet-Scale Problem Across All Technologies



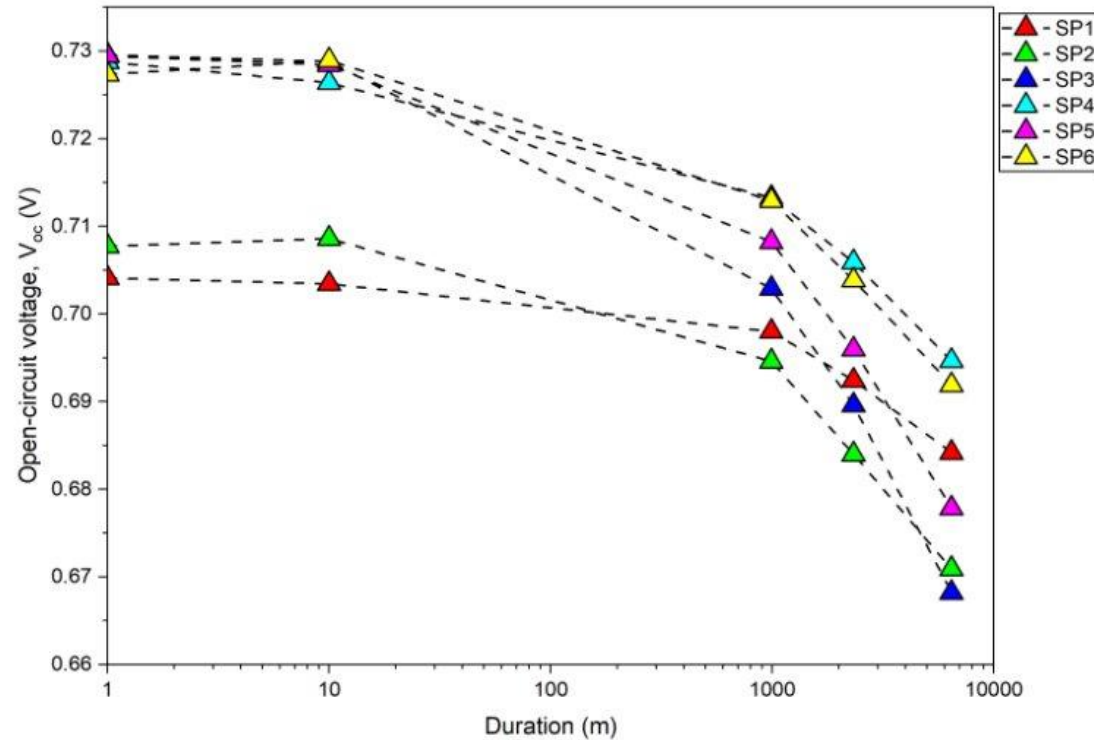
Accelerated cell-level UVID: Days, Not Months



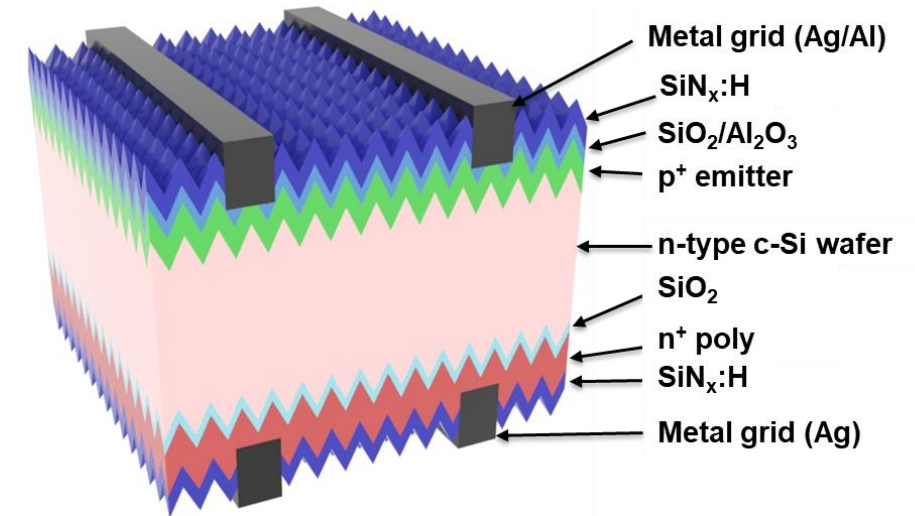
- We can accelerate UVID using UV-B compared to UV-A
- Only degradation at the **TOPCon front**, no degradation at the TOPCon rear as UV is fully absorbed in the poly-Si layer (this may change when using poly fingers in the near future)



Accelerated cell level UVID: Days, Not Months

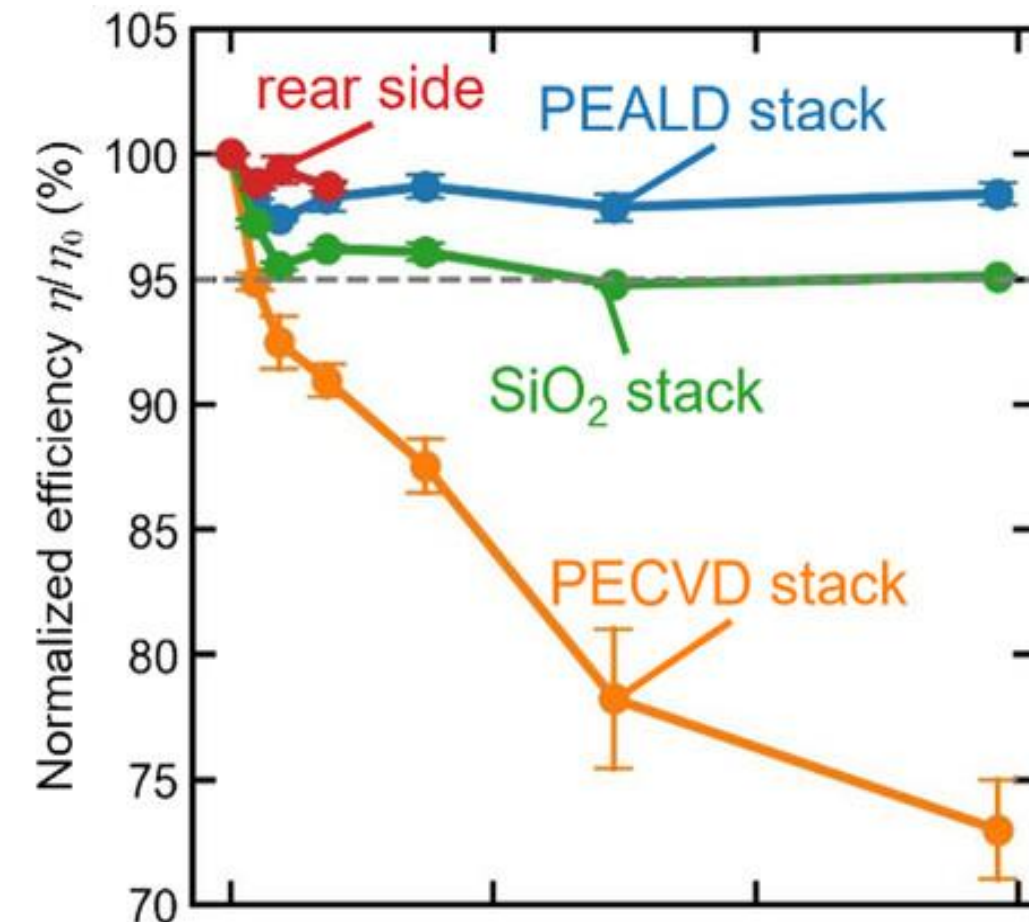


- We accelerate UVID using UV-B compared to UV-A
- Test can be used to check your supply chain
- Significant spread in cell UVID sensitivity observed in our testing (up to a factor of 5!)



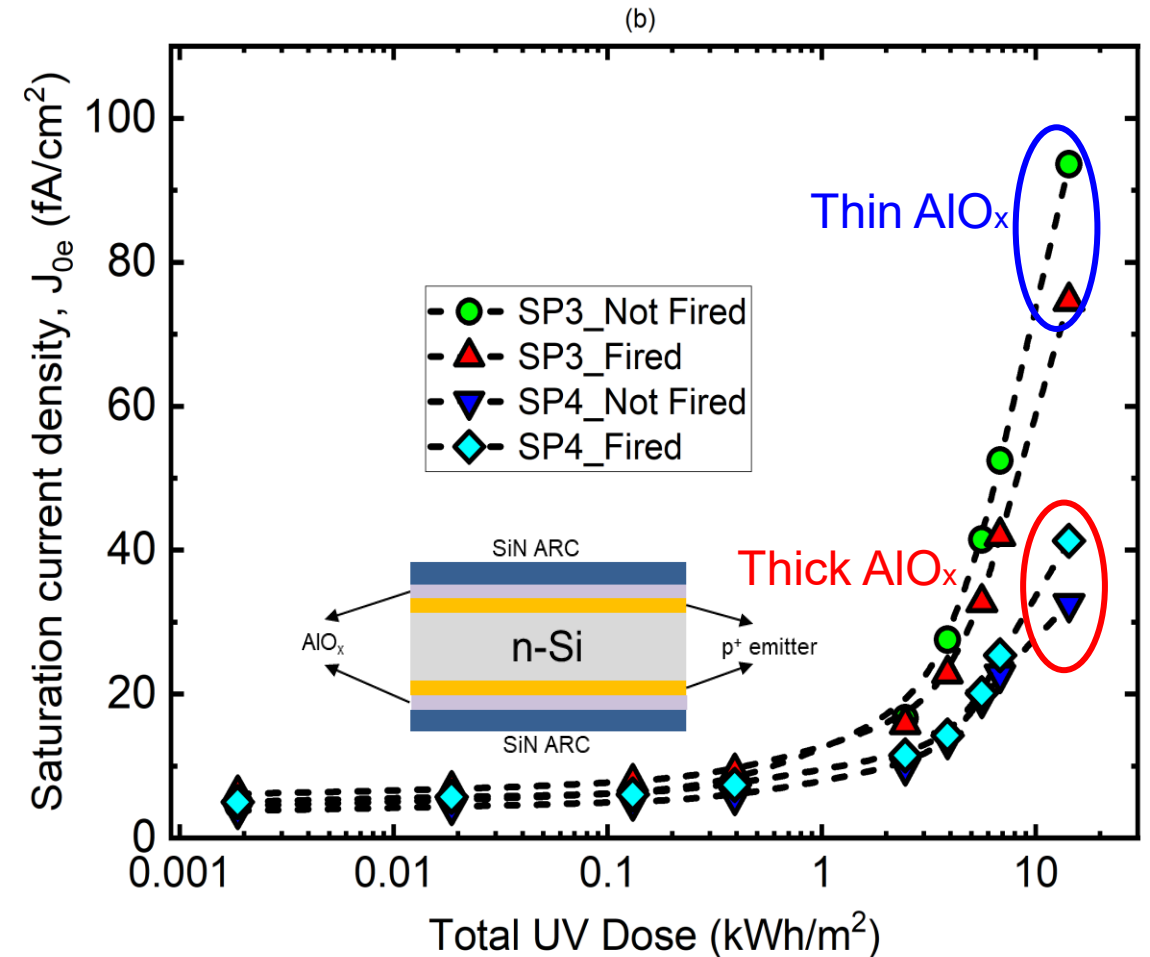
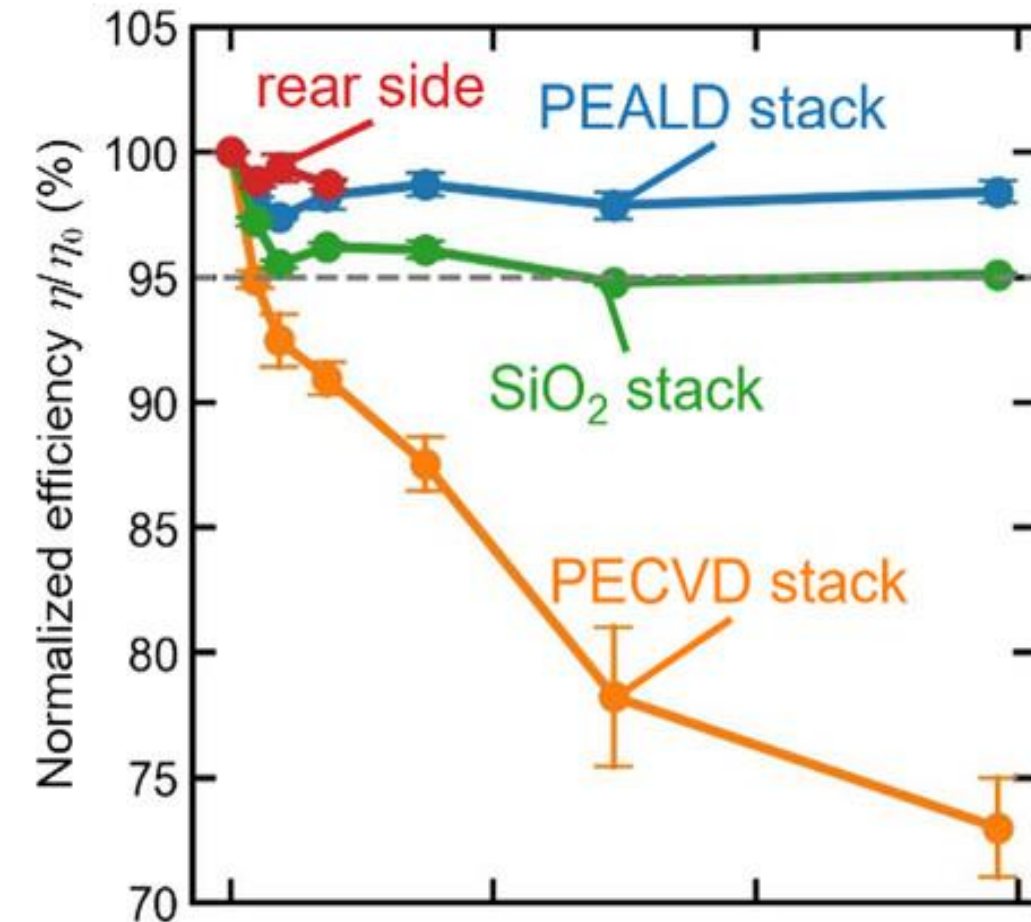
Reducing UVID at the cell level

- Significantly higher UVID when using PECVD vs ALD for AlO_x film deposition
- Higher quality silicon oxide (SiO_2) film reduces UVID

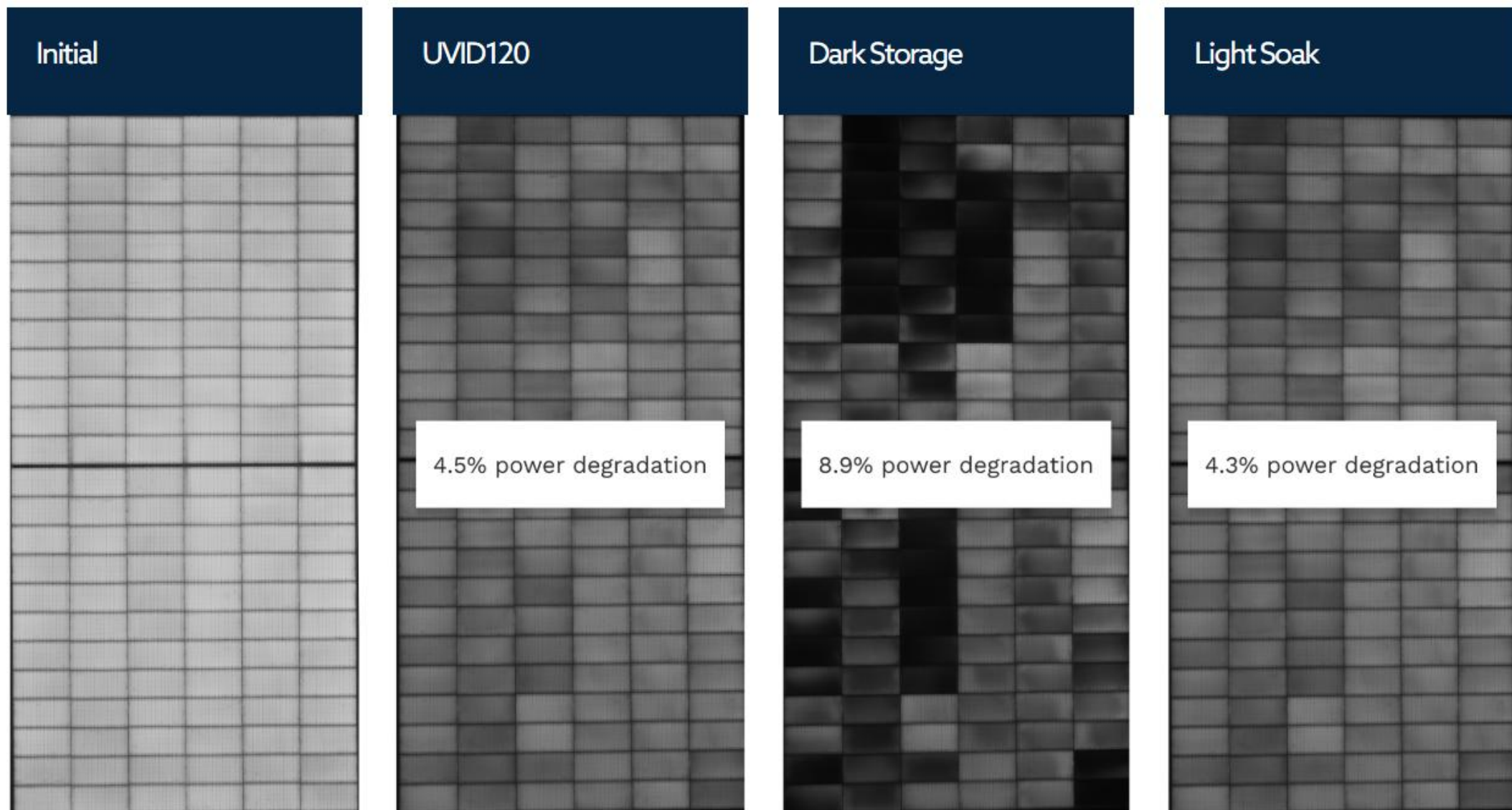


Reducing UVID at the cell level

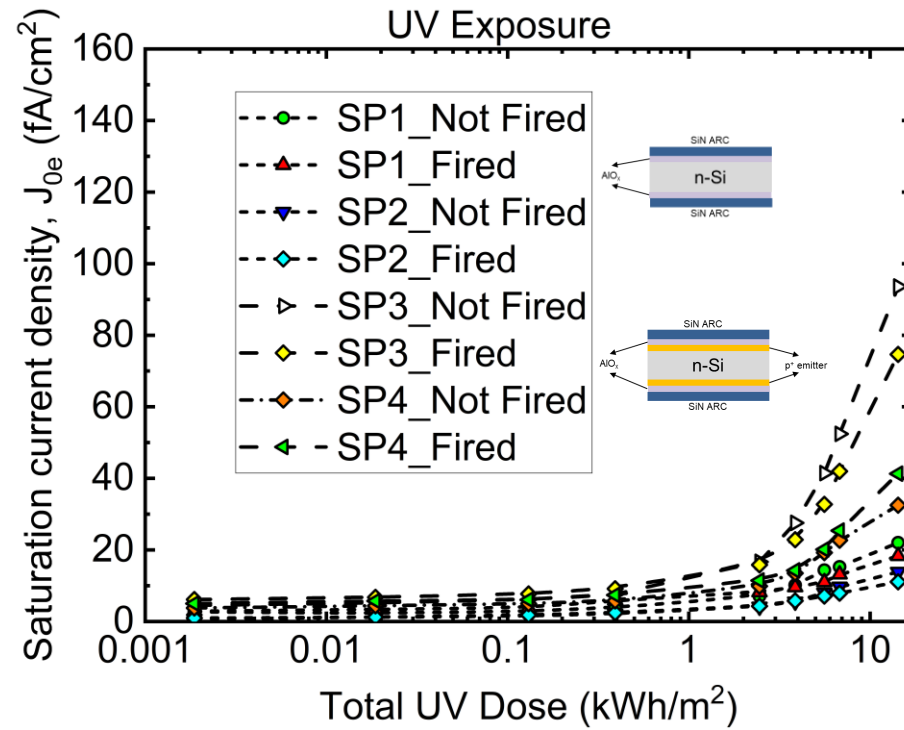
- Significantly higher UVID when using PECVD vs ALD for AlO_x film deposition
- Higher quality silicon oxide (SiO_2) film reduces UVID
- Thicker ALD films reduce UVID



Dark Storage Metastability: Challenge for Testing

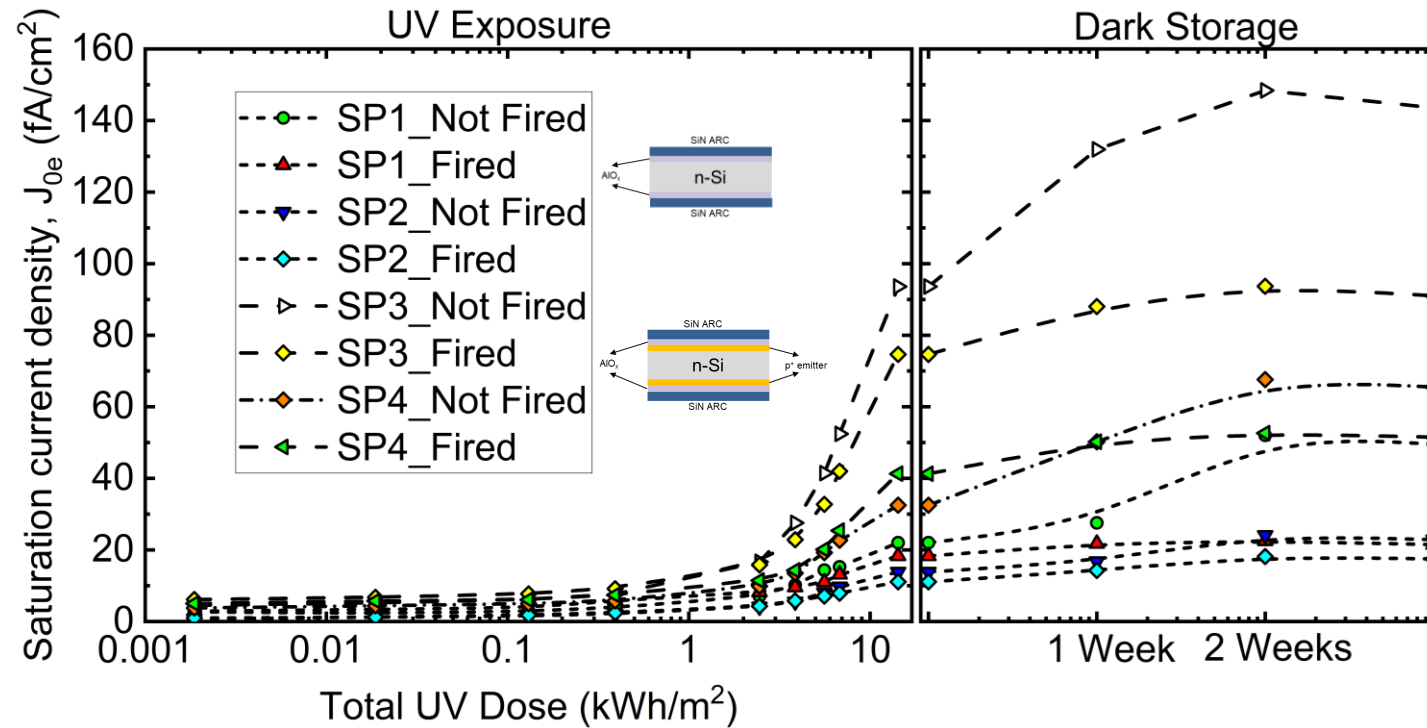


Metastability: Degradation Continues in the Dark, Recovers on Anneal



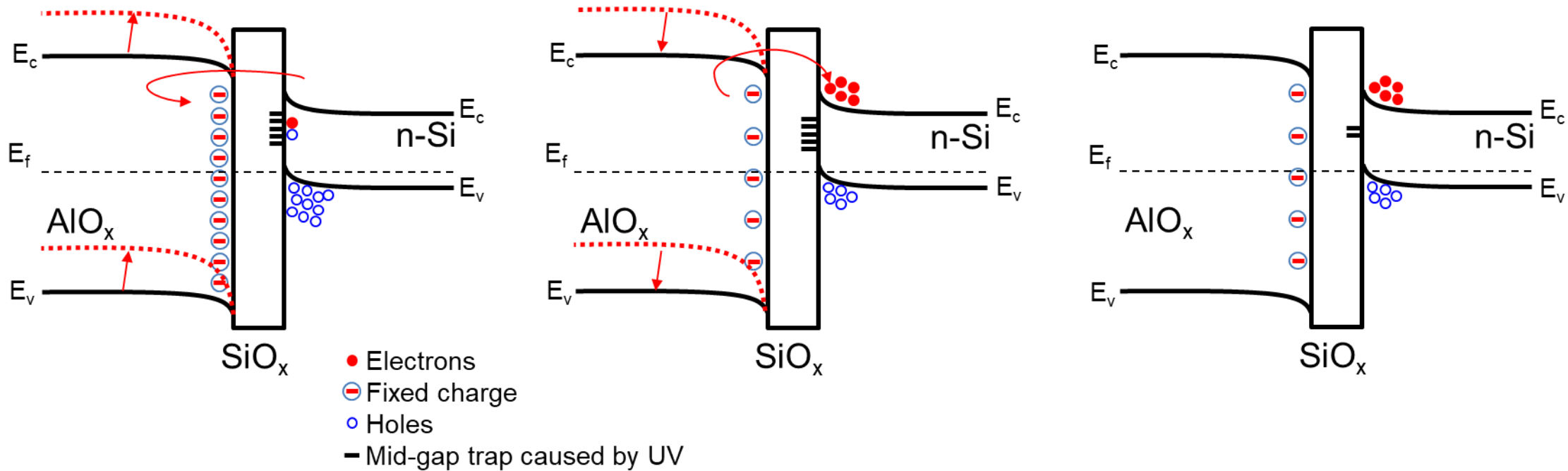
- **UV:** Rapid rise in recombination

Metastability: Degradation Continues in the Dark, Recovers on Anneal



- **UV:** Rapid rise in recombination
- **Dark storage:** Degradation continues, worst in unstable samples
- **Annealing:** Low-T anneal restores J_{0e} to near initial values

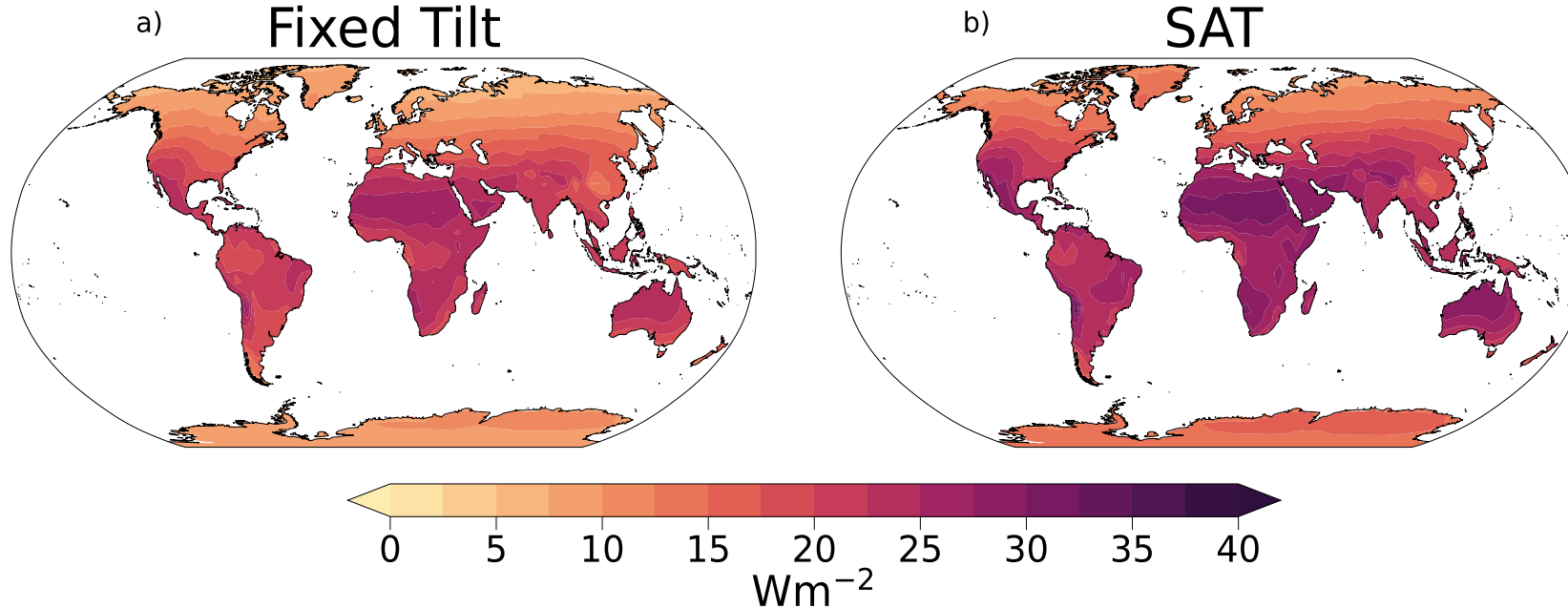
Proposed UVID mechanism



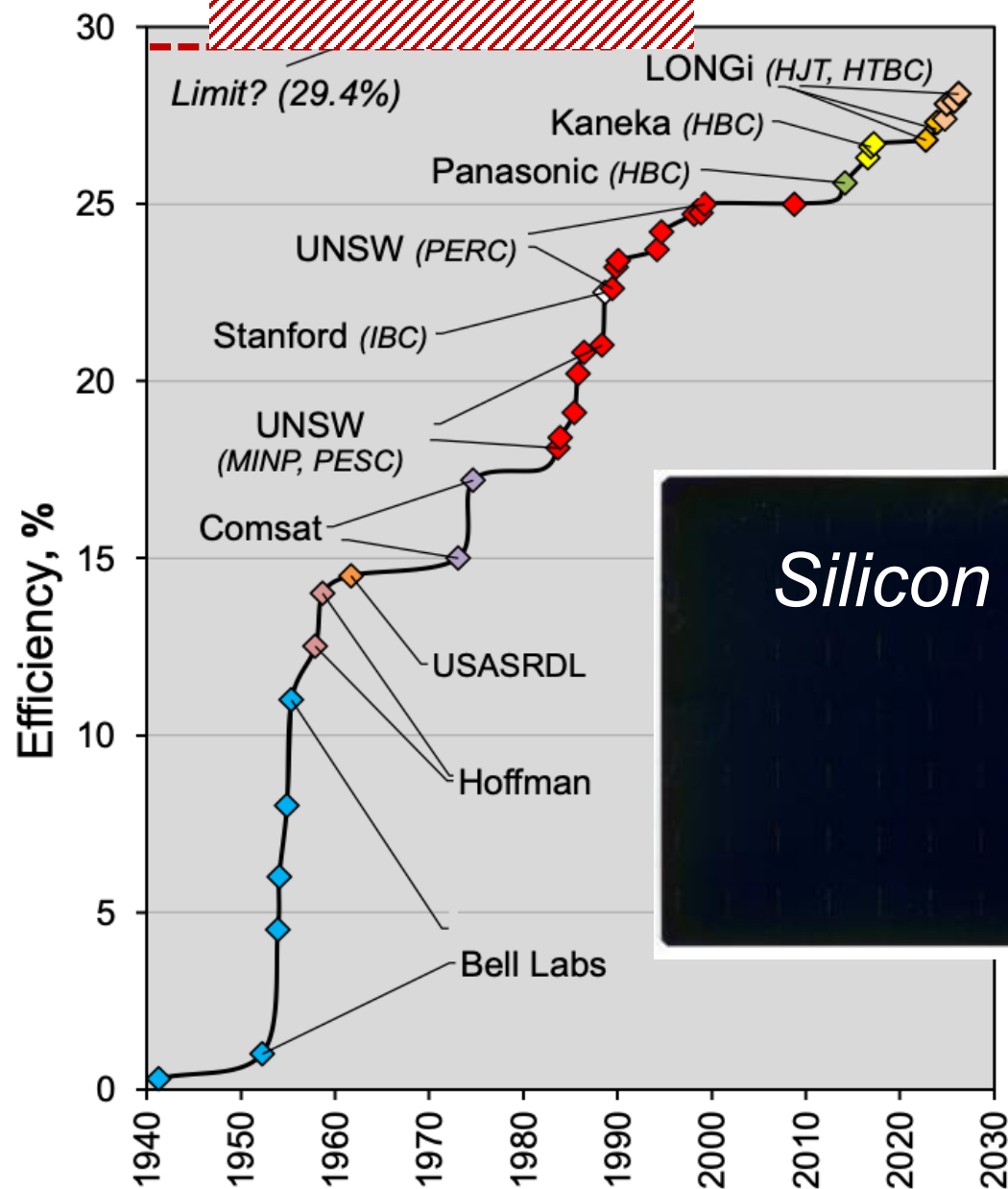
- **UV:** Si–H bond breakage in SiN_x and interface $\uparrow D_{it}$, but charge trapping boosts Q_f
- **Dark storage:** D_{it} stable; Q_f released $\rightarrow$ higher recombination
- **Recovery:** Anneal diffuses H, $\downarrow D_{it}$, restores passivation.

Global Scale UV modelling

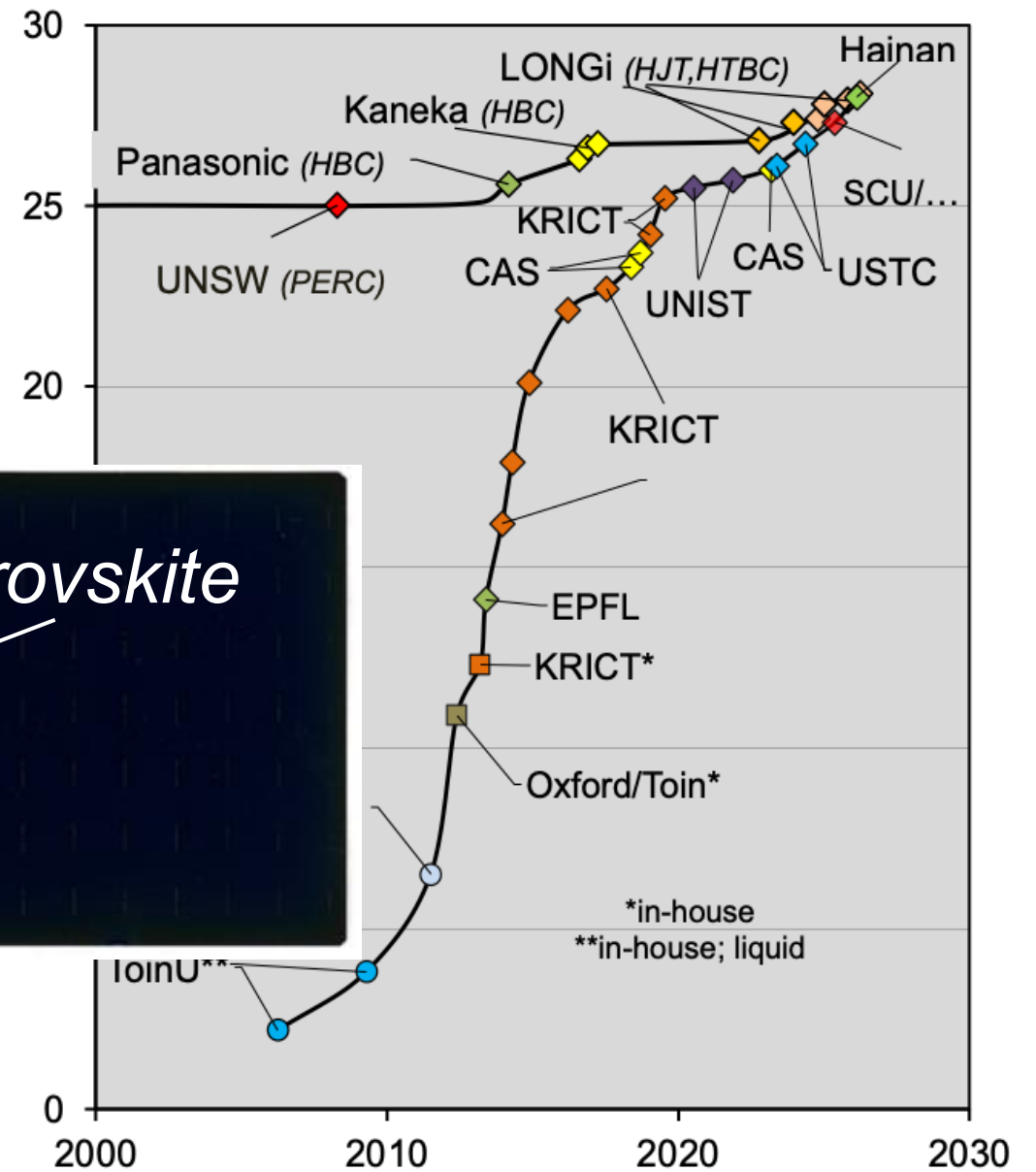
UV radiation on PV systems



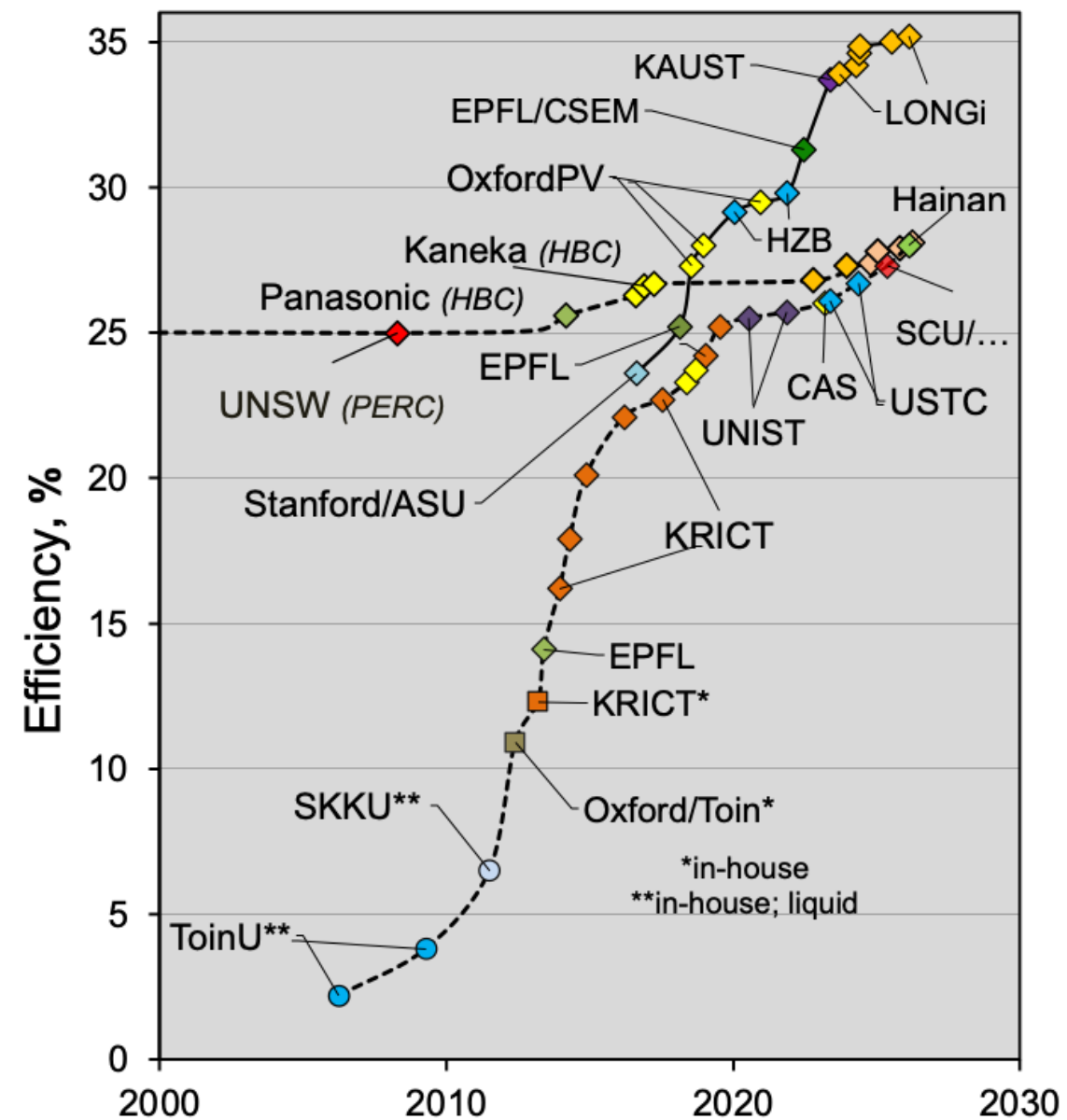
- Previous models could only model global UV
- We developed a model to calculate angle- and wavelength-dependent UV from satellite data that is as accurate as resource-intensive ray tracing



Silicon vs perovskite

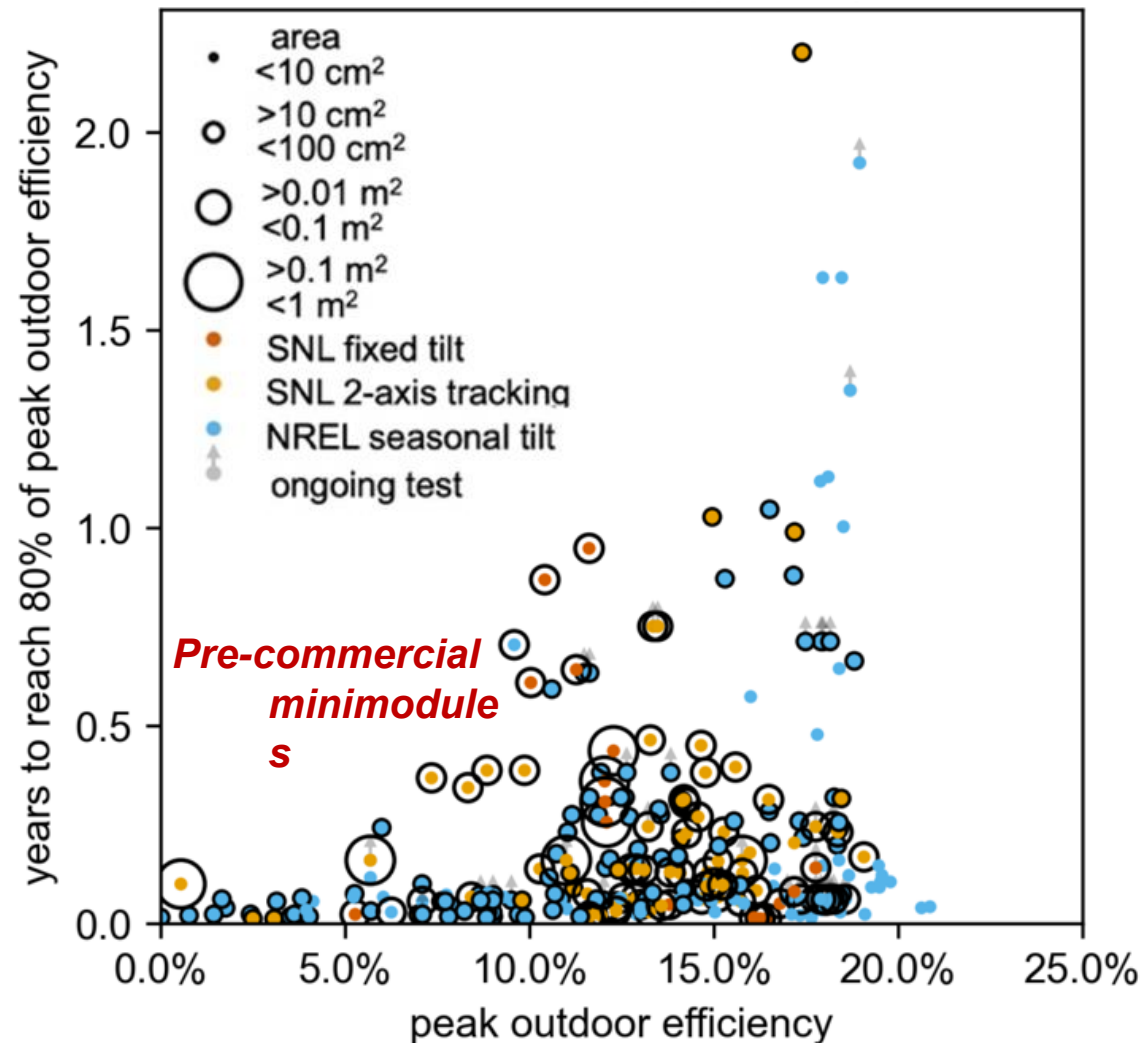


*Silicon plus perovskite
in tandem cells!*

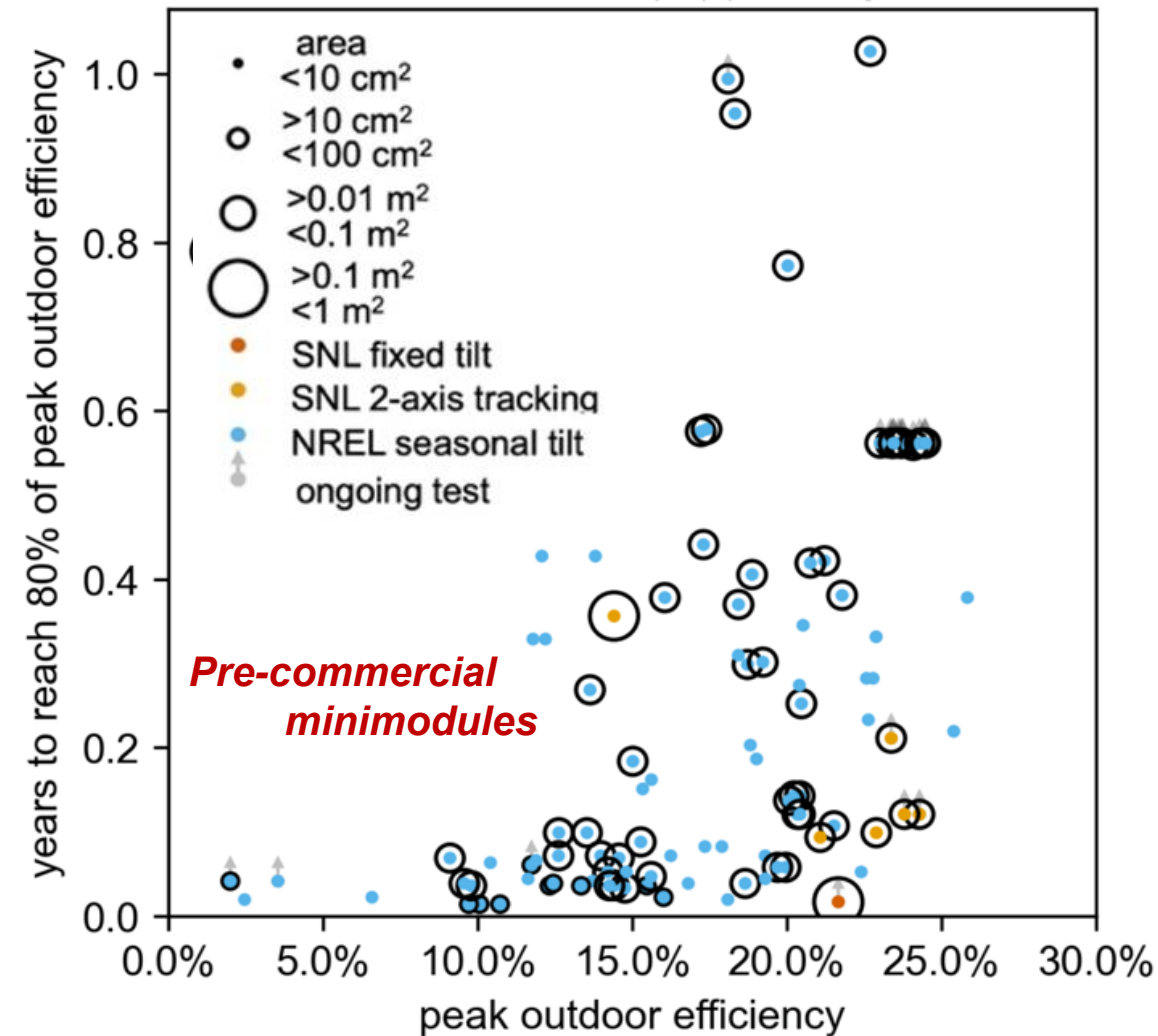


Perovskite? Stability?

Single junction



Tandem



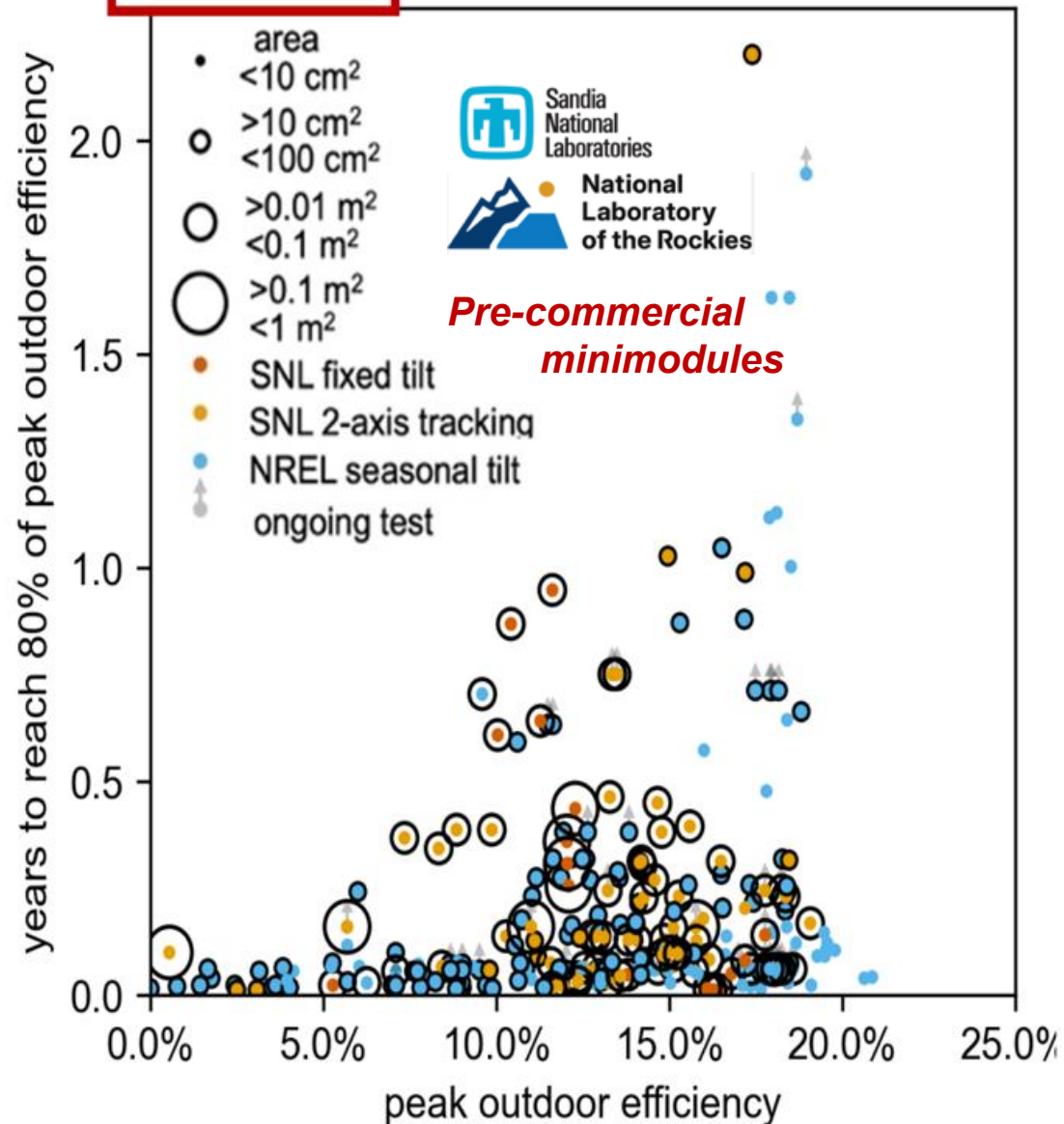


Independent third-party testing required!
UNSW initiated this in May 2025

- 
- *Field-testing commercial (& pre-commercial) perovskite modules*
 - *Voluntary anonymized participation – all key players involved*
 - *Quarterly reports – anonymized data for whole field*
 - *Failed module diagnostics with mitigation suggestions*

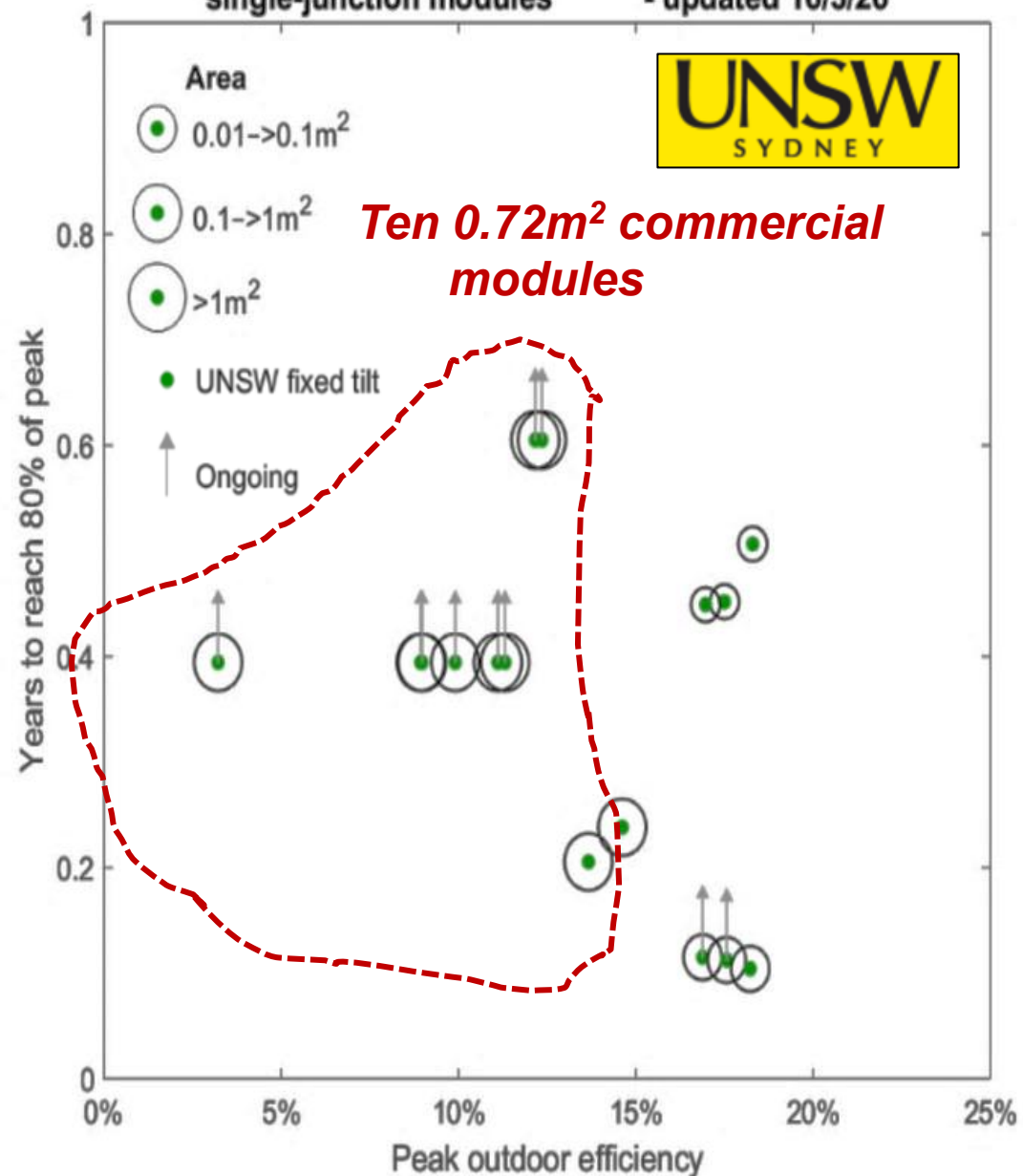
single-junction modules

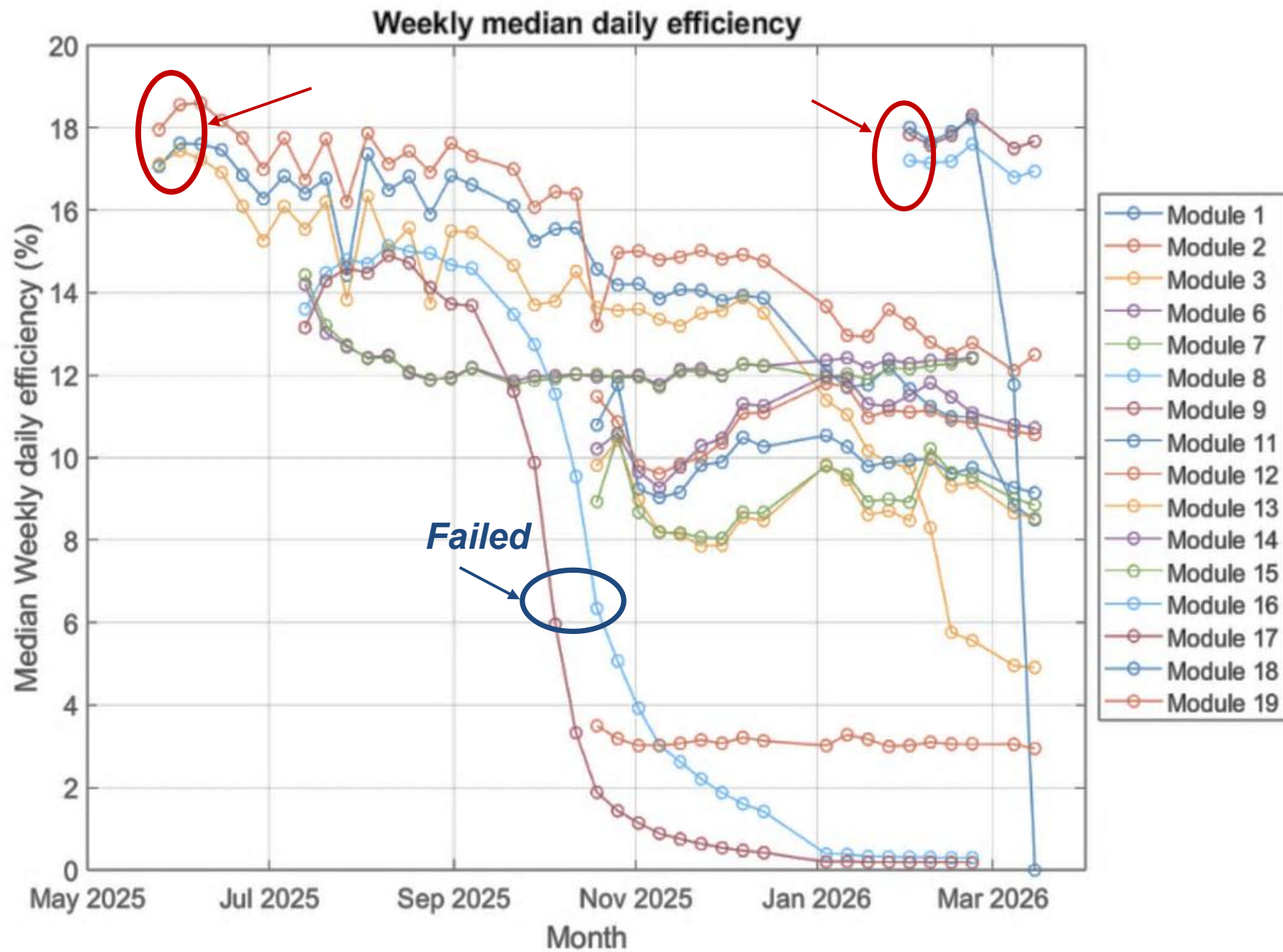
Updated 2026-05-07



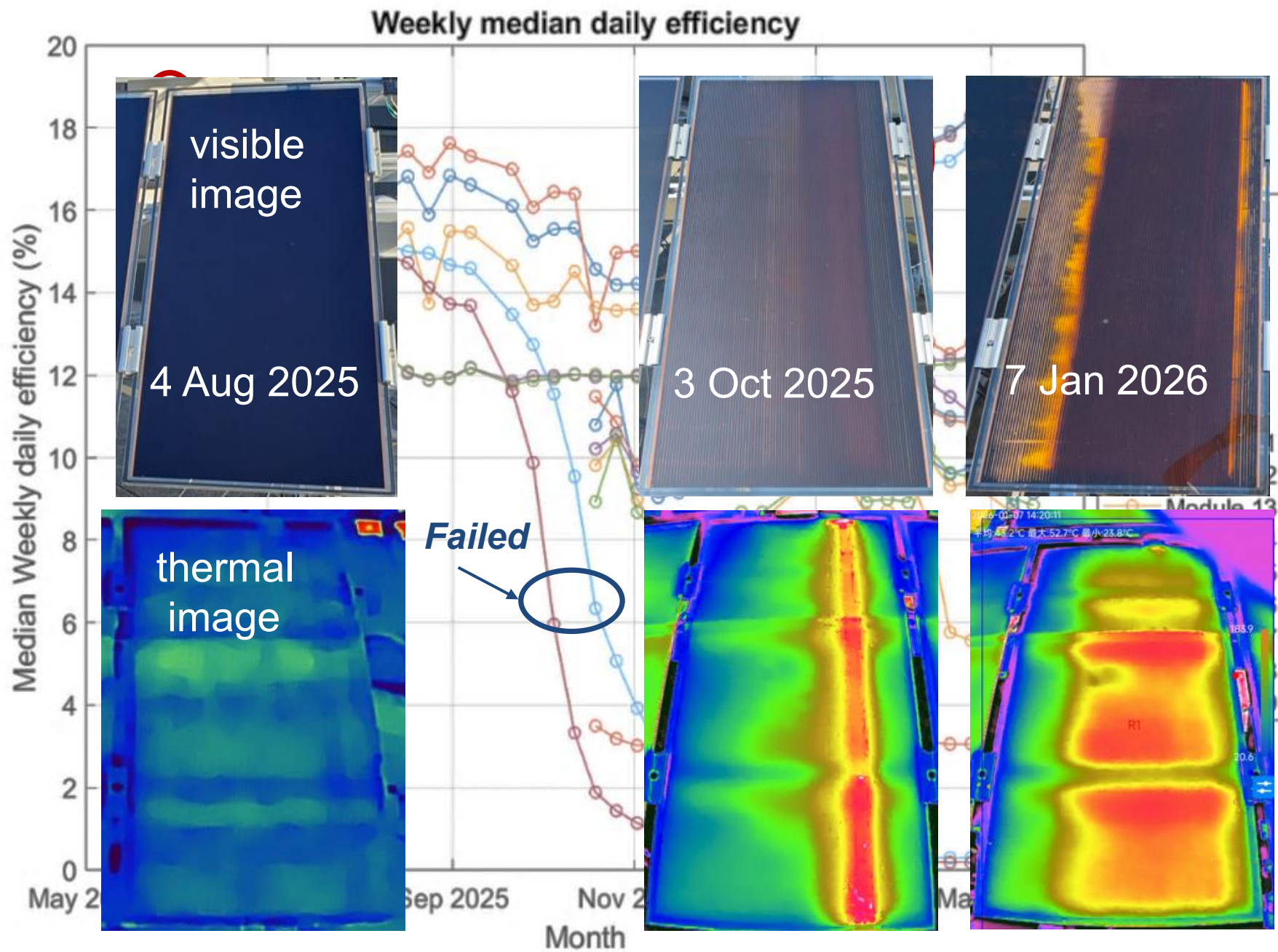
single-junction modules

- updated 16/3/26





Green *et al.*, SNEC Plenary, 2026



Phase II

Pyranometers
UV, PAR

Security camera

Perovskite modules

Si module
(power)

Si module
(reference)

Green *et al.*, SNEC Plenary, 2026

Beyond the Standard: From Mechanism to Bankable Lifetime

Standards detect infant failures, they **don't predict or guarantee** 25+ year lifetime. **The problems are technology-specific and mechanistic, and so are the solutions.**

WHAT WE FOUND

HJT & TOPCon carry unique failure modes absent in PERC



Encapsulant additives react with metallisation & dielectric films



UVID is mechanistic — up to 5× spread across the supply chain



Perovskite has a real, unresolved reliability gap



WHAT WE CAN DO FOR YOU **Foresight PV**



Cell-level failure-mode diagnostics

Reproduce your DH/field failures, identify root cause — 10–100× faster than module testing

Encapsulant & BOM screening

Flag additive–metallisation incompatibilities before they cost 25-year reliability

Accelerated UVID qualification + yield modelling

Rank sensitivity in days; UVID built into lifetime predictions, not derate guesses

Independent perovskite field-testing

Join the anonymised program @UNSW, ahead of GW deployment

Running in  P2AgentX: our yield & degradation models give your farm's AI the means to detect and act on losses before they compound.

